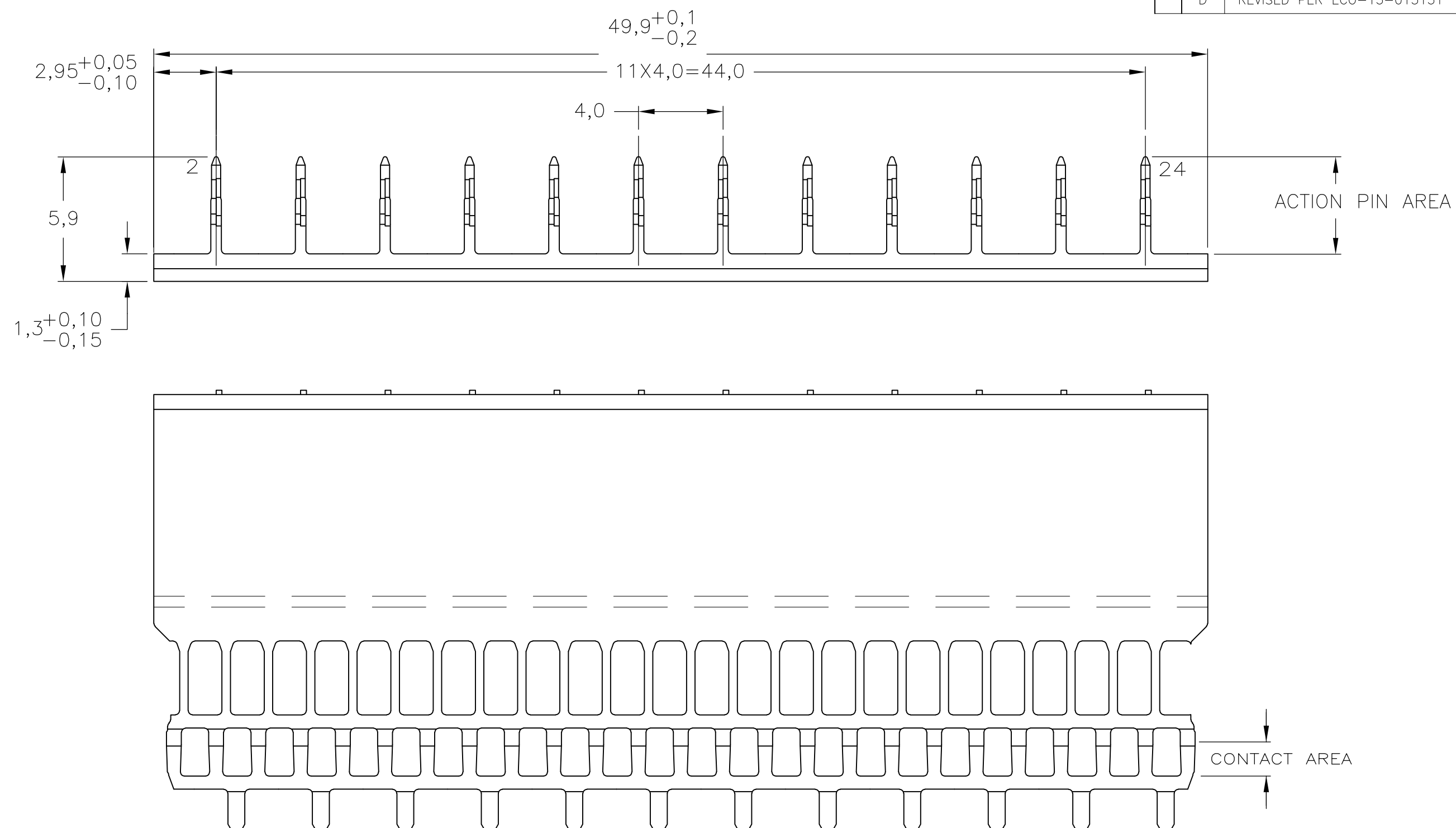


- △ GENERAL PLATING SPECIFICATION: UNDERPLATING
(ENTIRE CONTACT): 1,27µm NICKEL MIN.AND ACTION
PIN: 0,5µm TIN MIN.
FOR PLATING OF MATING SURFACES SEE PERFORMANCE LEVEL
SHOWN IN PART NUMBER TABLE.
- △ MATERIAL; PHOSPHORBRONZE.
- △ ROW "r" 12 PLATED THROUGH HOLES FOR LOWERSHIELD.
- △ HOLE PATTERN FOR FEMALE CONNECTOR TYPE B-25 COLUMNS WITH
UPPERSHIELD, 125+13 PLATED-THROUGH HOLES AT 2x2mm SQUARE GRID.
- 5 MAX. BOARD THICKNESS 3,5 mm.
- △ SHIELDS LUBRICATED WITH BELLCORE APPROVED LUBRICANT.
TECHNICAL REF: TR-NWT-001217 ISSUE 1, SEPT. 1992.
- △ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101
PERFORMANCE LEVEL 2.
- △ CONFORMS TO ALL TESTING ACCORDING IEC 61076-4-101
PERFORMANCE LEVEL 1.
- △ CONNECTOR TESTED AND QUALIFIED AGAINST TELCORDIA GR-1217-CORE
QUALITY LEVEL III,CENTRAL OFFICE APPLICATIONS.
- △ 0.76µm MIN GOLD PLATING AT MATING SURFACE.

  		4-5338110-0
  		5338110-9
 		5338110-2
FINISH	MATERIAL	PARTNUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN K.N.KIRAN		13AUG04		 TE Connectivity	
		CHK B.MOOLJ		25MAR05			
DIMENSIONS: mm		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD B.MOOLJ		NAME	
		±0.2		PRODUCT SPEC		Z-PACK 2mm HM GROUND RETURN LOWER SHIELD TYPE B-25 COLUMNS	
		1-PLC		108-19082			
		2-PLC		APPLICATION SPEC			
		3-PLC		114-19029			
MATERIAL		FINISH		WEIGHT		RESTRICTED TO	
-		-		-		-	
CUSTOMER DRAWING						SCALE 5:1 SHEET 1 OF 1 REV D	